SN74LS74A

Dual D-Type Positive Edge-Triggered Flip-Flop

The SN74LS74A dual edge-triggered flip-flop utilizes Schottky TTL circuitry to produce high speed D-type flip-flops. Each flip-flop has individual clear and set inputs, and also complementary Q and $\overline{Q}$ outputs.

Information at input D is transferred to the Q output on the positive-going edge of the clock pulse. Clock triggering occurs at a voltage level of the clock pulse and is not directly related to the transition time of the positive-going pulse. When the clock input is at either the HIGH or the LOW level, the D input signal has no effect.

MODE SELECT – TRUTH TABLE

OPERATING MODE	INPUTS			OUTPUTS	
	$\overline{S_D}$	$\overline{C_D}$	D	Q	$\overline{Q}$
Set	L	H	X	H	L
Reset (Clear)	H	L	X	L	H
*Undetermined	L	L	X	H	H
Load “1” (Set)	H	H	h	H	L
Load “0” (Reset)	H	H	l	L	H

* Both outputs will be HIGH while both $\overline{S}_D$ and $\overline{C}_D$ are LOW, but the output states are unpredictable if $\overline{S}_D$ and $\overline{C}_D$ go HIGH simultaneously. If the levels at the set and clear are near V_{IL} maximum then we cannot guarantee to meet the minimum level for V_{OH}.

H, h = HIGH Voltage Level

L, l = LOW Voltage Level

X = Don’t Care

l, h (q) = Lower case letters indicate the state of the referenced input (or output) one set-up time prior to the HIGH to LOW clock transition.

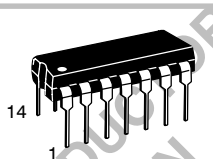
GUARANTEED OPERATING RANGES

Symbol	Parameter	Min	Typ	Max	Unit
V_{CC}	Supply Voltage	4.75	5.0	5.25	V
T_A	Operating Ambient Temperature Range	0	25	70	°C
I_{OH}	Output Current – High			–0.4	mA
I_{OL}	Output Current – Low			8.0	mA

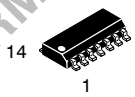
ON Semiconductor®

http://onsemi.com

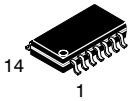
LOW POWER SCHOTTKY



PLASTIC
N SUFFIX
CASE 646



SOIC
D SUFFIX
CASE 751A



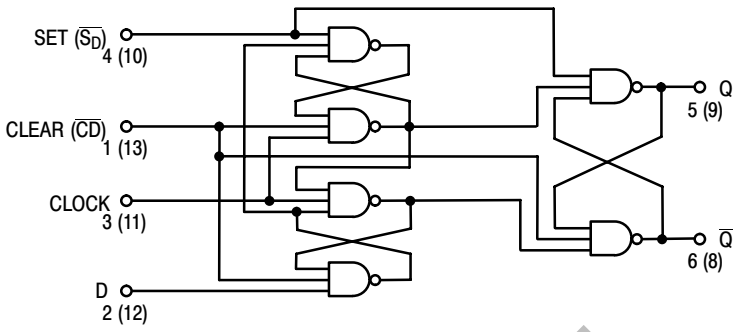
SOEIAJ
M SUFFIX
CASE 965

ORDERING INFORMATION

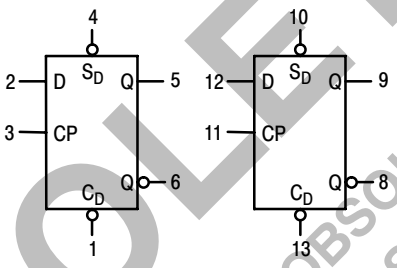
Device	Package	Shipping
SN74LS74AN	14 Pin DIP	2000 Units/Box
SN74LS74AD	SOIC–14	55 Units/Rail
SN74LS74ADR2	SOIC–14	2500/Tape & Reel
SN74LS74AM	SOEIAJ–14	See Note 1
SN74LS74AMEL	SOEIAJ–14	See Note 1

1. For ordering information on the EIAJ version of the SOIC package, please contact your local ON Semiconductor representative.

LOGIC DIAGRAM (Each Flip-Flop)



LOGIC SYMBOL



V_{CC} = PIN 14
GND = PIN 7

DC CHARACTERISTICS OVER OPERATING TEMPERATURE RANGE (unless otherwise specified)

Symbol	Parameter	Limits Min	Typ	Max	Unit	Test Conditions	
V_{IH}	Input HIGH Voltage	2.0			V	Guaranteed Input HIGH Voltage for All Inputs	
V_{IL}	Input LOW Voltage			0.8	V	Guaranteed Input LOW Voltage for All Inputs	
V_{IK}	Input Clamp Diode Voltage		−0.65	−1.5	V	V_{CC} = MIN, I_{IN} = −18 mA	
V_{OH}	Output HIGH Voltage	2.7	3.5		V	V_{CC} = MIN, I_{OH} = MAX, V_{IN} = V_{IH} or V_{IL} per Truth Table	
V_{OL}	Output LOW Voltage		0.25	0.4	V	I_{OL} = 4.0 mA	V_{CC} = V_{CC} MIN, V_{IN} = V_{IL} or V_{IH} per Truth Table
			0.35	0.5	V	I_{OL} = 8.0 mA	
I_{IH}	Input High Current Data, Clock Set, Clear			20 40	μA	V_{CC} = MAX, V_{IN} = 2.7 V	
	Data, Clock Set, Clear			0.1 0.2	mA	V_{CC} = MAX, V_{IN} = 7.0 V	
I_{IL}	Input LOW Current Data, Clock Set, Clear			−0.4 −0.8	mA	V_{CC} = MAX, V_{IN} = 0.4 V	
I_{OS}	Output Short Circuit Current (Note 2)	−20		−100	mA	V_{CC} = MAX	
I_{CC}	Power Supply Current			8.0	mA	V_{CC} = MAX	

2. Not more than one output should be shorted at a time, nor for more than 1 second.

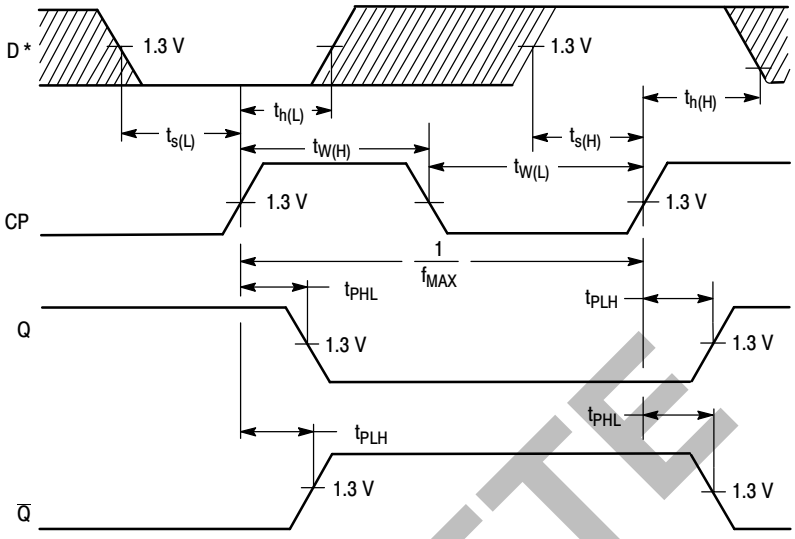
AC CHARACTERISTICS (T_A = 25°C, V_{CC} = 5.0 V)

Symbol	Parameter	Limits Min	Typ	Max	Unit	Test Conditions	
f_{MAX}	Maximum Clock Frequency	25	33		MHz	Figure 1	V_{CC} = 5.0 V C_L = 15 pF
t_{PLH} t_{PHL}	Clock, Clear, Set to Output		13 25	25 40	ns ns	Figure 1	

AC SETUP REQUIREMENTS (T_A = 25°C)

Symbol	Parameter	Limits Min	Typ	Max	Unit	Test Conditions	
$t_{W(H)}$	Clock	25			ns	Figure 1	V_{CC} = 5.0 V
$t_{W(L)}$	Clear, Set	25			ns	Figure 2	
t_s	Data Setup Time — HIGH	20			ns	Figure 1	
	LOW	20			ns		
t_h	Hold Time	5.0			ns	Figure 1	

AC WAVEFORMS



*The shaded areas indicate when the input is permitted to change for predictable output performance.

Figure 1. Clock to Output Delays, Data Set-Up and Hold Times, Clock Pulse Width

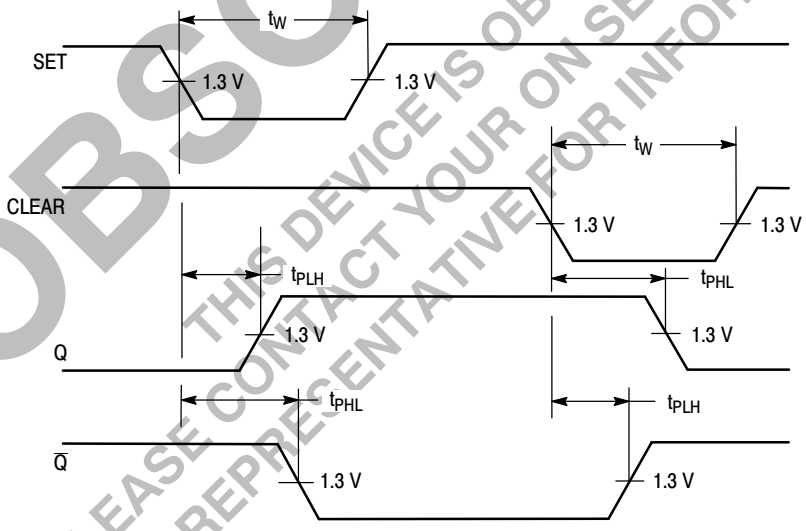
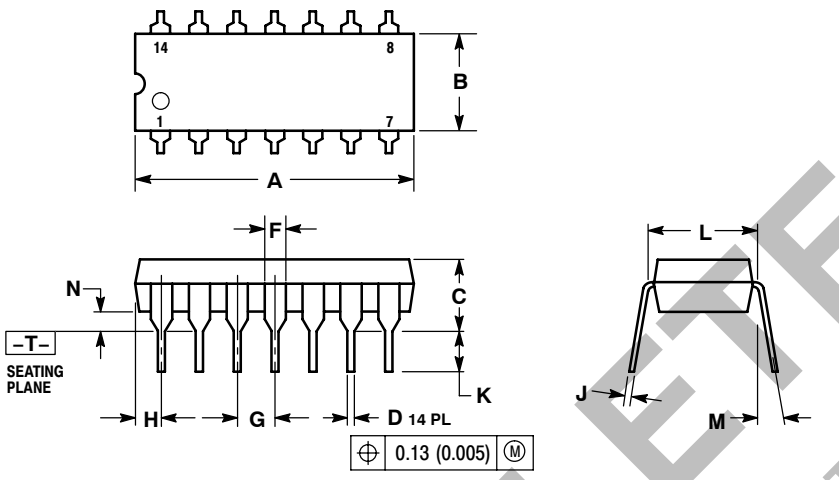


Figure 2. Set and Clear to Output Delays, Set and Clear Pulse Widths

PACKAGE DIMENSIONS

N SUFFIX
PLASTIC PACKAGE
CASE 646–06
ISSUE M

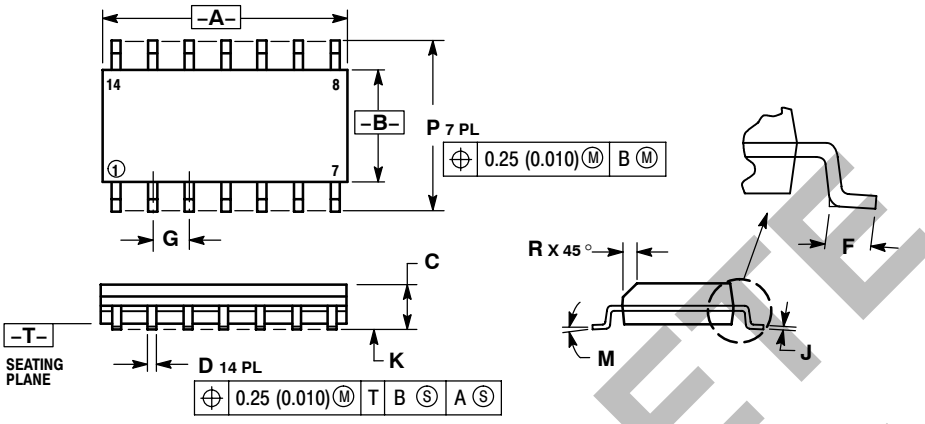


NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: INCH.
3. DIMENSION L TO CENTER OF LEADS WHEN FORMED PARALLEL.
4. DIMENSION B DOES NOT INCLUDE MOLD FLASH.
5. ROUNDED CORNERS OPTIONAL.

	INCHES		MILLIMETERS	
DIM	MIN	MAX	MIN	MAX
A	0.715	0.770	18.16	18.80
B	0.240	0.260	6.10	6.60
C	0.145	0.185	3.69	4.69
D	0.015	0.021	0.38	0.53
F	0.040	0.070	1.02	1.78
G	0.100 BSC		2.54 BSC	
H	0.052	0.095	1.32	2.41
J	0.008	0.015	0.20	0.38
K	0.115	0.135	2.92	3.43
L	0.290	0.310	7.37	7.87
M	---	10°	---	10°
N	0.015	0.039	0.38	1.01

PACKAGE DIMENSIONS

D SUFFIX
PLASTIC SOIC PACKAGE
CASE 751A–03
ISSUE F

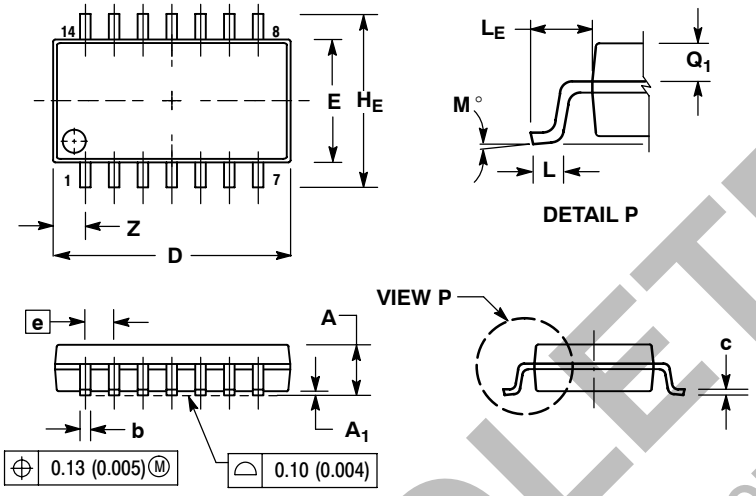


NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSIONS A AND B DO NOT INCLUDE MOLD PROTRUSION.
4. MAXIMUM MOLD PROTRUSION 0.15 (0.006) PER SIDE.
5. DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.127 (0.005) TOTAL IN EXCESS OF THE D DIMENSION AT MAXIMUM MATERIAL CONDITION.

	MILLIMETERS		INCHES	
DIM	MIN	MAX	MIN	MAX
A	8.55	8.75	0.337	0.344
B	3.80	4.00	0.150	0.157
C	1.35	1.75	0.054	0.068
D	0.35	0.49	0.014	0.019
F	0.40	1.25	0.016	0.049
G	1.27 BSC		0.050 BSC	
J	0.19	0.25	0.008	0.009
K	0.10	0.25	0.004	0.009
M	0 °	7 °	0 °	7 °
P	5.80	6.20	0.228	0.244
R	0.25	0.50	0.010	0.019

PACKAGE DIMENSIONS

M SUFFIX
SOEIAJ PACKAGE
CASE 965−01
ISSUE O



NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH OR PROTRUSIONS AND ARE MEASURED AT THE PARTING LINE. MOLD FLASH OR PROTRUSIONS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.
4. TERMINAL NUMBERS ARE SHOWN FOR REFERENCE ONLY.
5. THE LEAD WIDTH DIMENSION (b) DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 (0.003) TOTAL IN EXCESS OF THE LEAD WIDTH DIMENSION AT MAXIMUM MATERIAL CONDITION. DAMBAR CANNOT BE LOCATED ON THE LOWER RADIUS OR THE FOOT. MINIMUM SPACE BETWEEN PROTRUSIONS AND ADJACENT LEAD TO BE 0.46 (0.018).

	MILLIMETERS		INCHES	
DIM	MIN	MAX	MIN	MAX
A	---	2.05	---	0.081
A_1	0.05	0.20	0.002	0.008
b	0.35	0.50	0.014	0.020
c	0.18	0.27	0.007	0.011
D	9.90	10.50	0.390	0.413
E	5.10	5.45	0.201	0.215
e	1.27 BSC		0.050 BSC	
H_E	7.40	8.20	0.291	0.323
0.50	0.50	0.85	0.020	0.033
L_E	1.10	1.50	0.043	0.059
M	0 °	10 °	0 °	10 °
Q_1	0.70	0.90	0.028	0.035
Z	---	1.42	---	0.056

PUBLICATION ORDERING INFORMATION

LITERATURE FULFILLMENT:
Literature Distribution Center for ON Semiconductor
P.O. Box 5163, Denver, Colorado 80217 USA
Phone: 303−675−2175 or 800−344−3860 Toll Free USA/Canada
Fax: 303−675−2176 or 800−344−3867 Toll Free USA/Canada
Email: orderlit@onsemi.com

N. American Technical Support: 800−282−9855 Toll Free USA/Canada
Europe, Middle East and Africa Technical Support:
Phone: 421 33 790 2910
Japan Customer Focus Center
Phone: 81−3−5773−3850

ON Semiconductor Website: **www.onsemi.com**

Order Literature: http://www.onsemi.com/orderlit

For additional information, please contact your local Sales Representative